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PATENT

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MULTI-LAYER INTERCONNECT MODULE AND METHOD OF INTERCONNECTION

ABSTRACT OF THE DISCLOSURE

An electronic module includes an interconnect module having a plurality of metal layers separated by a plurality of dielectric layers in a stacked structure with electronic components mounted on one surface of the module. The electronic components are selectively interconnected by drilling via holes completely through all dielectric layers with a conductive material such as solder in each via contacting metal layers to be interconnected and each metal layer which is not connected by a via having a metal pattern devoid of metal at the via location. For via connecting non-ground layers, there will be a patch of solder mask on the backside ground layer to electrically prevent this via from inadvertently connecting to ground.

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